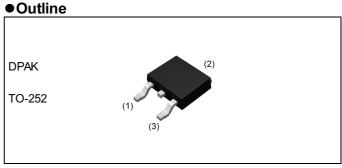
Pch -60V -48A Power MOSFET

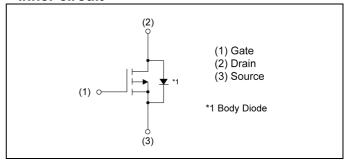
V _{DSS}	-60V
R _{DS(on)} (Max.)	30mΩ
I _D	±48A
P _D	77W



Features

Low on-resistance Pb-free plating; RoHS compliant 100% Avalanche tested AEC-Q101 qualified

●Inner circuit



Packaging specifications

- r working opcomoducite						
	Packing	Embossed Tape				
	Reel size (mm)	330				
Туре	Tape width (mm)	16				
	Quantity (pcs)	2500				
	Taping code	TL				
	Marking	RD3L04BBJ				

Application

ADAS/Info./Lighting/Body

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	-60	V	
Continuous dusin summent	T _c = 25°C	I _D *1	±48	Α
Continuous drain current	T _a = 25°C	I _D *5	±14.5	Α
Pulsed drain current	I _{DP} *2	±96	Α	
Gate - Source voltage	V_{GSS}	+5/-20	V	
Avalanche current, single pulse		I _{AS} *3	-31	Α
Avalanche energy, single pulse		E _{AS} *3	34.9	mJ
Dower discipation		P _D *1	77	W
Power dissipation	P _D *5	6.43	W	
Junction temperature	Tj	175	°C	
Operating junction and storage t	T _{stg}	-55 to +175	°C	

●Thermal resistance

Parameter	Sumbol	Values			Linit
raianietei	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	-	1.94	°C/W
Thermal resistance, junction - ambient	R _{thJA} *5	-	23.3	-	°C/W

●Electrical characteristics (T_a = 25°C)

Davanastan	Company of	Canditions	Values			Lloit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j} I_D = -1 \text{mA}$ referenced to 25°C		-50	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -48V, V _{GS} = 0V	-	-	-1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = +5/-20V, V_{DS} = 0V$	-	ı	±500	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -787 \mu A$	-1.0	-	-2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I _D = -787μA referenced to 25°C	-	3.7	-	mV/°C	
Static drain - source	D *4	V _{GS} = -10V, I _D = -10A	-	23	30	O	
on - state resistance	R _{DS(on)} *4	V _{GS} = -4.5V, I _D = -10A	-	26	34	mΩ	
Gate resistance	R_{G}	f=1MHz, open drain	-	9.2	-	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = -5V, I _D = -10A	14	-	-	S	

^{*1} T_c =25°C , Limited only by maximum junction temperature T_j =175°C.

^{*2} Pw ≤10µs , Duty cycle ≤1%

^{*3} L=0.05mH, V_{DD} =-30V, R_G =25 Ω , Starting T_j =25 $^{\circ}$ C, See Fig.3-1,3-2

^{*4} Pulsed

^{*5} Device on 2s2p FR4 PCB Defined in accordance with JEDEC standards (JESD51-5,-7). PCB is vertical in still air.

● Electrical characteristics (T_a = 25°C)

Davanastan	Cy reads ad	Canditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Uniil	
Input capacitance	C _{iss}	V _{GS} = 0V	-	2450	-		
Output capacitance	C _{oss}	V _{DS} = -30V	-	185	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	140	-		
Turn - on delay time	t _{d(on)} *4	V _{DD} ≃ -30V,V _{GS} = -10V	-	10	-		
Rise time	t _r *4	I _D = -10A	-	12	-		
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 3\Omega$	-	100	-	ns	
Fall time	t _f *4	$R_G = 1\Omega$	-	90	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *4		V _{GS} = -10V	-	48	-	
Total gate charge	Q _g *4	V _{DD} ≃ -30V		-	23	-	5 C
Gate - Source charge	Q _{gs} *4	I _D = -10A	V _{GS} = -4.5V	-	7	-	nC
Gate - Drain charge	Q _{gd} *4			-	10	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Daramatar	Cymphol	Conditions	Values			1.124
Parameter	Symbol	ol Conditions		Тур.	Max.	Unit
Continuous forward current	I _S *1	T = 25°C	-	-	-48	Α
Pulse forward current	l _{SP} *2	T _a = 25℃	-	-	-96	Α
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = -10A	-	-	-1.2	V
Reverse recovery time	t _{rr} *4	I _S = -10A, V _{GS} =0V	-	21	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = -100A/µs	-	25	-	nC

Fig.1 Power Dissipation Derating Curve

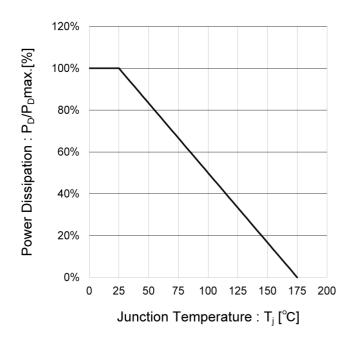
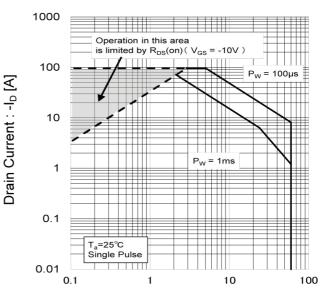


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

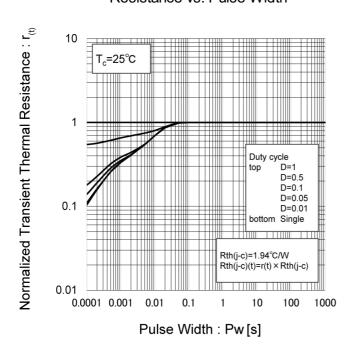


Fig.4 Single Pulse Maximum Power dissipation

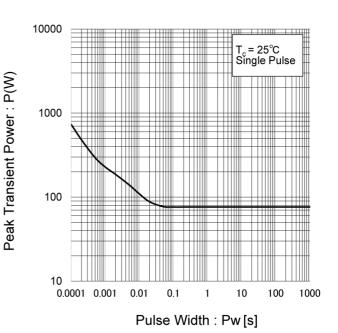


Fig.5 Typical Output Characteristics(I)

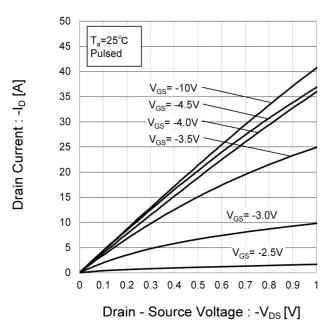
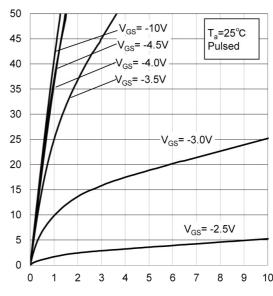


Fig.6 Typical Output Characteristics(II)



Drain Current : -I_D [A]

Drain - Source Voltage : -V_{DS} [V]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

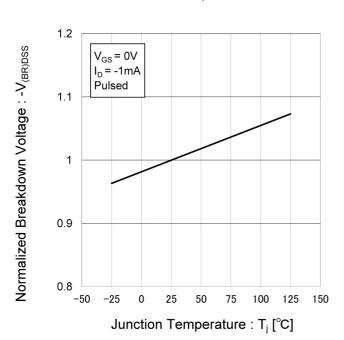


Fig.8 Typical Transfer Characteristics

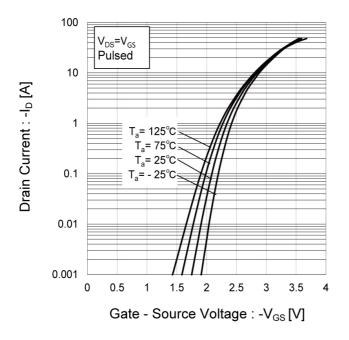


Fig.9 Gate Threshold Voltage vs. **Junction Temperature**

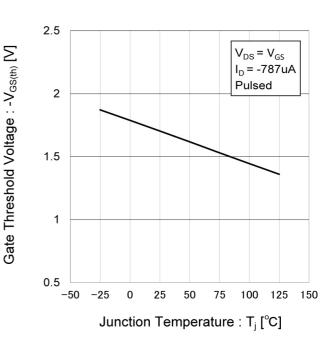
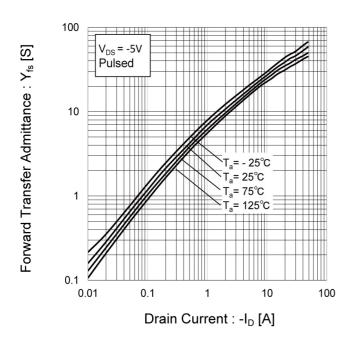


Fig.10 Forward Transfer Admittance vs. **Drain Current**



6/11

RD3L04BBJHRB

• Electrical characteristic curves

Fig.11 Drain Current Derating Curve

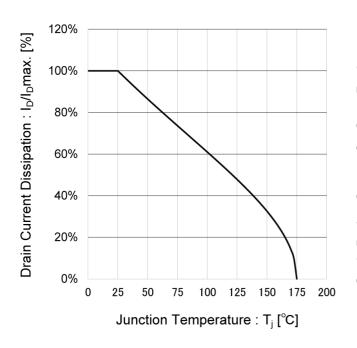


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Datasheet

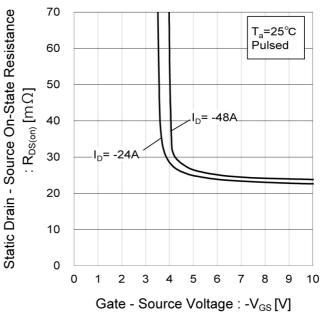


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

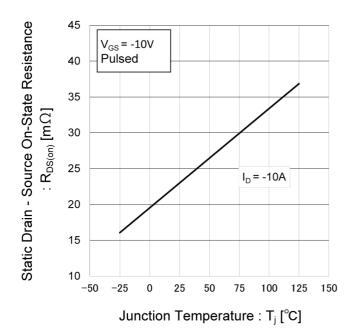


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

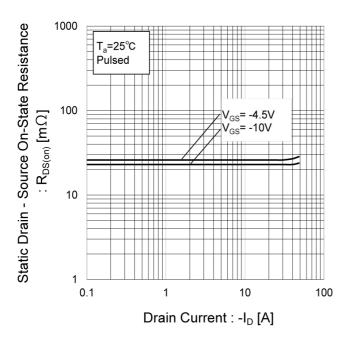
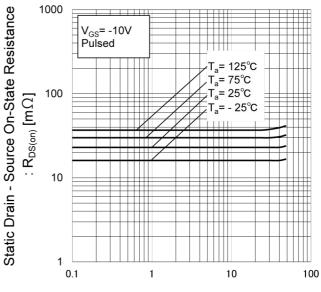


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)



Drain Current: -ID [A]

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

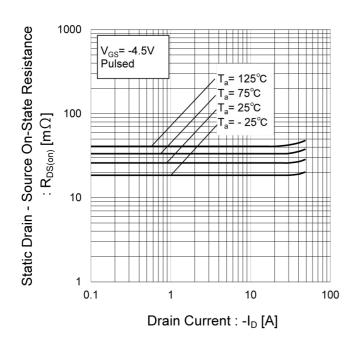


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

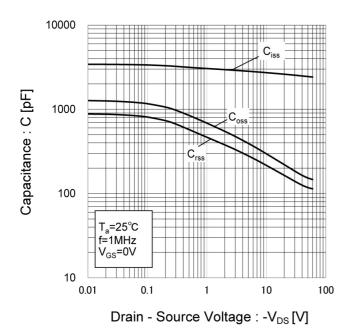


Fig.18 Switching Characteristics

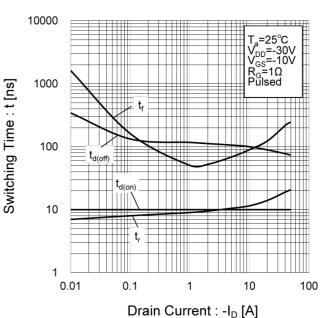


Fig.19 Dynamic Input Characteristics

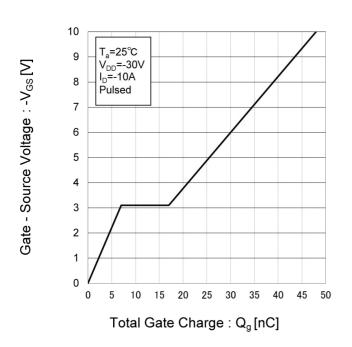
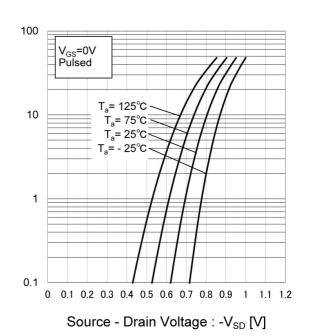


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : -I_s [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

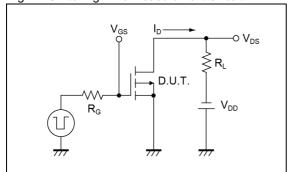


Fig.2-1 Gate Charge Measurement Circuit

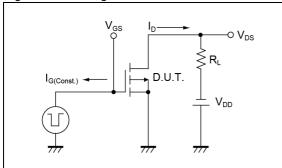


Fig.3-1 Avalanche Measurement Circuit

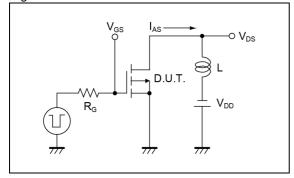


Fig.1-2 Switching Waveforms

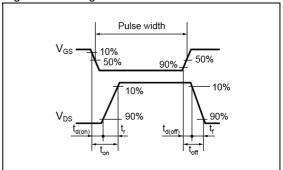


Fig.2-2 Gate Charge Waveform

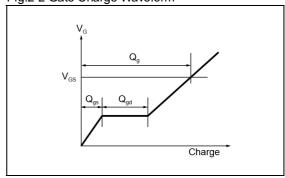
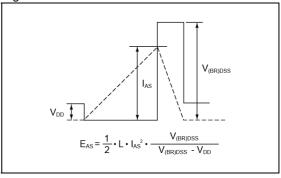
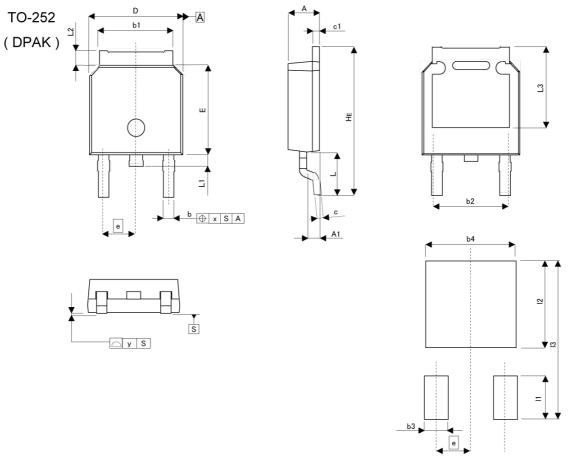


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INCI	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	201
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
Е	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	90	0.1	14
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.2	209
Х	-	0.25	-	0.010
у	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
DIIVI	MIN	MAX	MIN	MAX
b3	o -	1.10	-	0.043
b4	1-	5.40	-	0.213
l1	-	2.90	1	0.114
12	-	5.50	-	0.217
13	_	10.50	_	0.413

Dimension in mm/inches



Notice

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ſ	JÁPAN	USA	EU	CHINA
Ī	CLASSⅢ	CLASSIII	CLASS II b	СГУССШ
ſ	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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